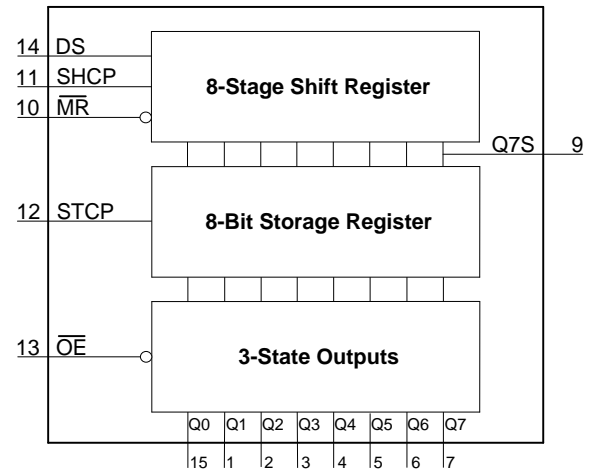


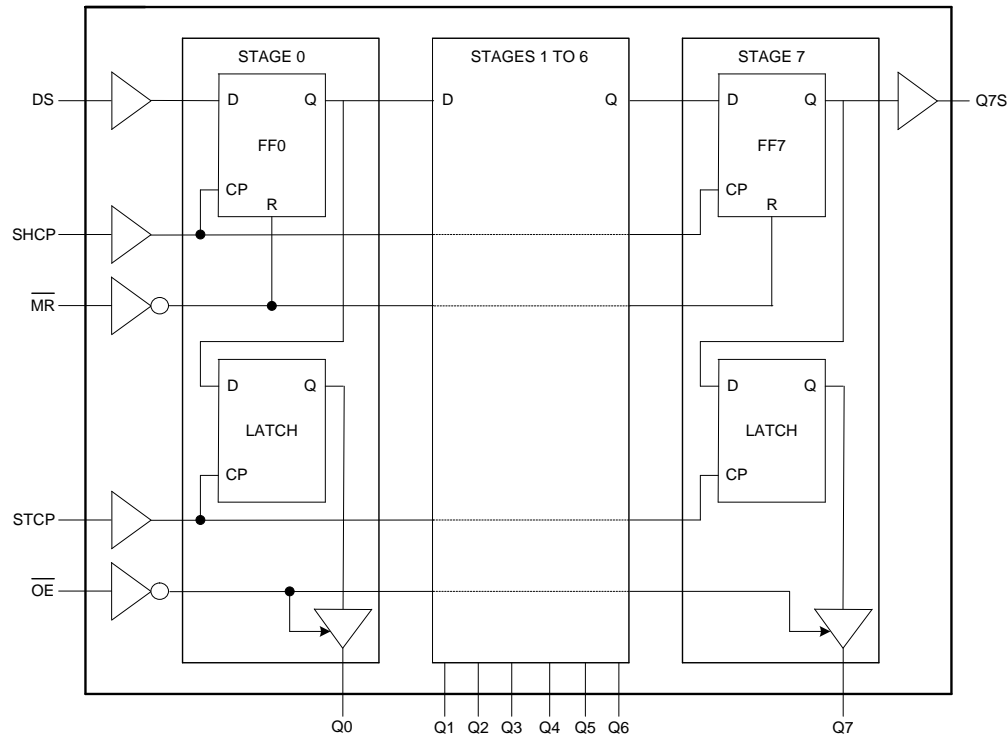
## Pin Descriptions

Pin Number	Pin Name	Function
1	Q1	Parallel Data Output 1
2	Q2	Parallel Data Output 2
3	Q3	Parallel Data Output 3
4	Q4	Parallel Data Output 4
5	Q5	Parallel Data Output 5
6	Q6	Parallel Data Output 6
7	Q7	Parallel Data Output 7
8	GND	Ground
9	Q7S	Serial Data Output
10	MR	Master Reset Input
11	SHCP	Shift Register Clock Input
12	STCP	Storage Register Clock Input
13	OE	Output Enable Input
14	DS	Serial Data Input
15	Q0	Parallel Data Output 0
16	VCC	Supply Voltage

## Functional Diagram



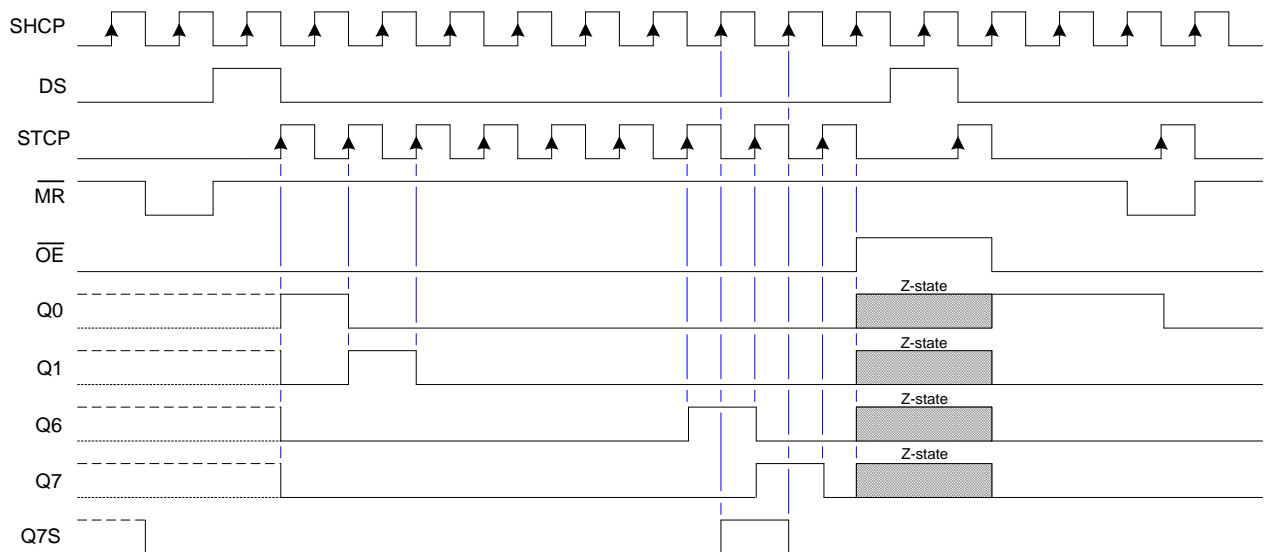
## Logic Diagram



## Functional Description and Timing Diagram

Control				Input	Output		Function
SHCP	STCP	$\overline{OE}$	$\overline{MR}$	DS	Q7S	Qn	
X	X	L	L	–	L	NC	Low-level asserted on MR clears shift register. Storage register is unchanged.
X	↑	L	L	–	L	L	Empty shift register transferred to storage register.
X	X	H	L	–	L	Z	Shift register remains clear; All Q outputs in Z state.
↑	X	L	H	–	Q6S	NC	HIGH is shifted into first stage of Shift Register Contents of each register shifted to next register. The content of Q6S has been shifted to Q7S and now appears on device pin Q7S.
X	↑	L	H	–	NC	QnS	Contents of shift register copied to storage register. With output now in active state the storage register contents appear on Q outputs.
↑	↑	L	H	–	Q6S	QnS	Contents of shift register copied to output register then shift register shifted.

H=HIGH Voltage State  
L=LOW Voltage State  
↑=LOW to HIGH Transition  
X= Don'T Care – High or Low (Not Floating)  
NC= No Change  
Z= High-Impedance State



**Absolute Maximum Ratings** (Note 4) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V <sub>CC</sub>	Supply Voltage Range	-0.5 to +7.0	V
V <sub>I</sub>	Input Voltage Range	-0.5 to +7.0	V
V <sub>O</sub>	Voltage Applied to Output in High or Low State	-0.3 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> < -0.5V	-20	mA
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> > V <sub>CC</sub> +0.5V	20	mA
I <sub>OK</sub>	Output Clamp Current V <sub>O</sub> < -0.5V	-20	mA
I <sub>OK</sub>	Output Clamp Current V <sub>O</sub> > V <sub>CC</sub> +0.5V	20	mA
I <sub>O</sub>	Continuous Output Current	Q7 Standard Output	±25
		Qn Bus Driver Outputs	±35
I <sub>CC</sub>	Continuous Current through V <sub>dd</sub> or GND	70	mA
I <sub>GND</sub>	Continuous Current through V <sub>dd</sub> or GND	-70	mA
T <sub>J</sub>	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
P <sub>TOT</sub>	Total Power Dissipation	500	mW

Note: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

**Recommended Operating Conditions** (Note 5) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage	–	2.0	6.0	V
V <sub>I</sub>	Input Voltage	–	0	V <sub>CC</sub>	V
V <sub>O</sub>	Output Voltage	Active Mode	0	V <sub>CC</sub>	V
Δt/ΔV	Input Transition Rise or Fall Rate	V <sub>CC</sub> = 2.0V	–	1000	ns/V
		V <sub>CC</sub> = 4.5V	–	500	
		V <sub>CC</sub> = 6.0V	–	400	–
T <sub>A</sub>	Operating Free-Air Temperature	–	-40	+125	°C

Note: 5. Unused inputs should be held at V<sub>CC</sub> or Ground.

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Parameter	Test Conditions	V <sub>CC</sub>	T <sub>A</sub> = +25°C			T <sub>A</sub> = -40°C to +85°C		T <sub>A</sub> = -40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V <sub>IH</sub>	High-Level Input Voltage	—	2.0V	1.5	1.2	—	1.5	—	1.5	—	V
		—	4.5V	3.15	2.4	—	3.15	—	3.15	—	
		—	6.0V	4.2	3.2	—	4.2	—	4.2	—	
V <sub>IL</sub>	Low-Level Input Voltage	—	2.0V	—	0.8	0.5	—	0.5	—	0.5	V
		—	4.5V	—	2.1	1.35	—	1.35	—	1.35	
		—	6.0V	—	2.8	1.8	—	1.8	—	1.8	
V <sub>OH</sub>	High-Level Output Voltage	I <sub>OH</sub> = -20μA All Outputs	2.0V	1.9	2.0	—	1.9	—	1.9	—	V
			4.5V	4.4	4.5	—	4.4	—	4.4	—	
			6.0V	5.9	6.0	—	5.9	—	5.9	—	
	Q7S Output	I <sub>OH</sub> = -4.0mA	4.5V	3.84	4.32	—	4.32	—	3.7	—	
		I <sub>OH</sub> = -5.2mA	6.0V	5.34	5.81	—	5.81	—	5.2	—	
	Qn Bus Outputs	I <sub>OH</sub> = -6.0mA	4.5V	3.84	4.32	—	4.32	—	3.7	—	
		I <sub>OH</sub> = -7.8mA	6.0V	5.34	5.81	—	5.81	—	5.2	—	
V <sub>OL</sub>	Low-Level Output Voltage	I <sub>OL</sub> = 20μA All Outputs	2.0V	—	0	0.1	—	0.1	—	0.1	V
			4.5V	—	0	0.1	—	0.1	—	0.1	
			6.0V	—	0	0.1	—	0.1	—	0.1	
	Q7S Output	I <sub>OL</sub> = 4.0mA	4.5V	—	.15	0.33	—	0.33	—	0.4	
		I <sub>OL</sub> = 5.2mA	6.0V	—	.16	0.33	—	0.33	—	0.4	
	Qn Bus Outputs	I <sub>OL</sub> = 6.0mA	4.5V	—	.15	0.33	—	0.33	—	0.4	
		I <sub>OL</sub> = 7.8mA	6.0V	—	.16	0.33	—	0.33	—	0.4	
I <sub>I</sub>	Input Current	V <sub>I</sub> = GND to 5.5V	6.0V	—	—	±0.1	—	± 1	—	± 1	μA
I <sub>OZ</sub>	OFF-State Output Current	Qn Internal High or Low V <sub>O</sub> = V <sub>CC</sub> or GND	6.0V	—	—	± 5	—	± 5	—	± 10	μA
I <sub>CC</sub>	Supply Current	V <sub>I</sub> = GND or V <sub>CC</sub> I <sub>O</sub> = 0	6.0V	—	—	8.0	—	80	—	160	μA
C <sub>i</sub>	Input Capacitance	V <sub>I</sub> = V <sub>CC</sub> or GND	6.0V	—	4	10	—	10	—	10	pF

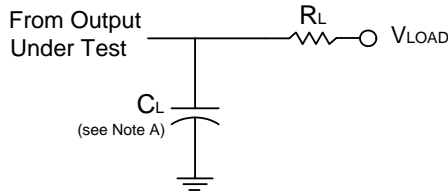
**Operating Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Parameter		Test Conditions	V <sub>CC</sub> = 5V	Unit
			Typ	
C <sub>pd</sub>	Power Dissipation Capacitance	f = 1 MHz All Outputs Switching-No Load	43	pF

**Switching Characteristics**

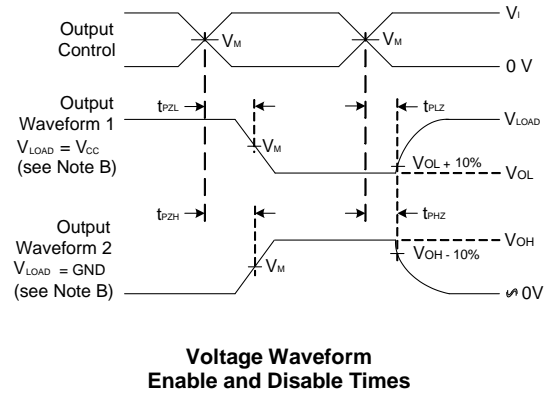
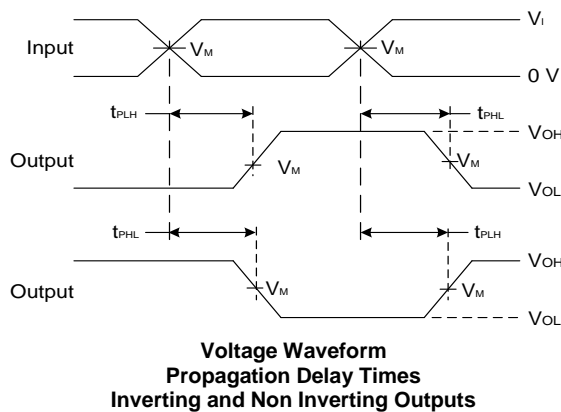
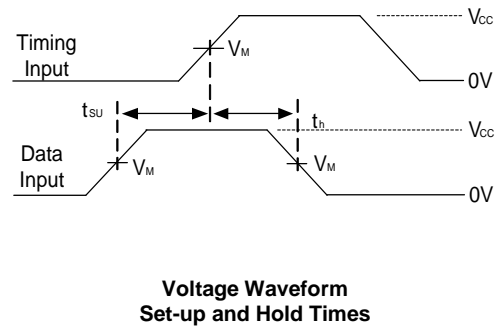
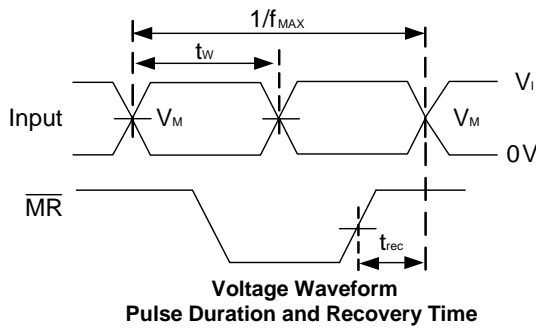
Symbol / Parameter	Pins	Test Conditions	V <sub>CC</sub>	T <sub>A</sub> = +25°C			-40°C to +85°C		-40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
f <sub>MAX</sub> Maximum Frequency	SHCP or STCP	Figure 1	2.0V	9	30	–	4.8	–	4	–	MHz
			4.5V	30	91	–	24	–	20	–	
			6.0V	35	108	–	28	–	24	–	
t <sub>w</sub> Pulse Width	SHCP HIGH or LOW	Figure 1	2.0V	75	17	–	95	–	110	–	ns
			4.5V	15	6	–	19	–	22	–	
			6.0V	13	5	–	16	–	19	–	
	STCP HIGH or LOW	Figure 1	2.0V	75	11	–	95	–	110	–	
			4.5V	15	4	–	19	–	22	–	
			6.0V	13	3	–	16	–	19	–	
	MR LOW	Figure 1	2.0V	75	17	–	95	–	110	–	
			4.5V	15	6	–	19	–	22	–	
			6.0V	13	5	–	16	–	19	–	
t <sub>su</sub> Set-up Time	DS to SHCP	Figure 1	2.0V	50	11	–	65	–	75	–	ns
			4.5V	10	4	–	13	–	15	–	
			6.0V	9	3	–	11	–	13	–	
	SHCP tp STCP	Figure 1	2.0V	75	22	–	95	–	110	–	ns
			4.5V	15	8	–	19	–	22	–	
			6.0V	13	7	–	16	–	19	–	
t <sub>H</sub> Hold Time	DS to SHCP	Figure 1	2.0V	3	-6	–	3	–	3	–	ns
			4.5V	3	-2	–	3	–	3	–	
			6.0V	3	-2	–	3	–	3	–	
t <sub>REC</sub> Recovery Time	MR to SHCP	Figure 1	2.0V	50	-19	–	65	–	75	–	ns
			4.5V	10	-7	–	13	–	15	–	
			6.0V	9	-6	–	11	–	13	–	
t <sub>PD</sub> Propagation Delay	SHCP to Q7S	Figure 1 C <sub>L</sub> =50pF	2.0V	–	52	160	–	200	–	240	ns
			4.5V	–	19	32	–	40	–	48	
			6.0V	–	15	27	–	34	–	41	
	STCP to Qn	Figure 1 C <sub>L</sub> =50pF	2.0V	–	55	175	–	220	–	265	ns
			4.5V	–	20	35	–	44	–	53	
			6.0V	–	16	30	–	37	–	45	
t <sub>PHL</sub> Propagation Delay	MR to Q7S	Figure 1 C <sub>L</sub> =50pF	2.0V	–	47	175	–	220	–	265	ns
			4.5V	–	17	35	–	44	–	53	
			6.0V	–	14	30	–	37	–	45	
t <sub>EN</sub> Enable Time	OE to Qn	Figure 1 C <sub>L</sub> =50pF	2.0V	–	47	150	–	190	–	225	ns
			4.5V	–	17	30	–	38	–	45	
			6.0V	–	14	26	–	33	–	38	
t <sub>DIS</sub> Disable Time	OE to Qn	Figure 1 C <sub>L</sub> =50pF	2.0V	–	41	150	–	190	–	225	ns
			4.5V	–	15	30	–	38	–	45	
			6.0V	–	12	26	–	33	–	38	

## Parameter Measurement Information



TEST	$V_{LOAD}$
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{CC}$
$t_{PHZ}/t_{PZH}$	GND

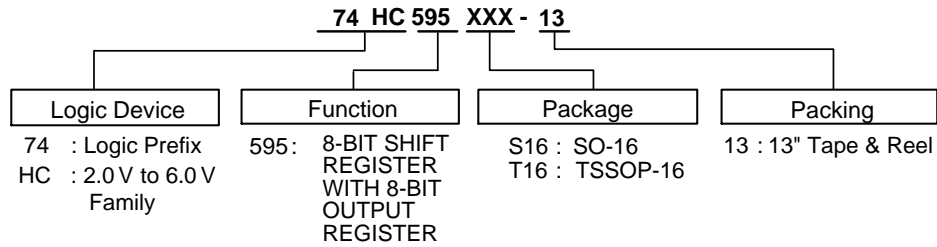
$V_{CC}$	Inputs		$V_M$	$C_L$
	$V_I$	$t_r/t_f$		
2.0V	$V_{CC}$	6ns	$V_{CC}/2$	50pF
4.5V	$V_{CC}$	6ns	$V_{CC}/2$	50pF
6.0V	$V_{CC}$	6ns	$V_{CC}/2$	50pF



- Notes:
- A. Includes test lead and test apparatus capacitance.
  - B. Output Waveform 1 depends on the internal  $Q_N$  node being low and behaves in this manner based on OE pin.  
Output Waveform 2 depends on the internal  $Q_N$  node being high and behaves in this manner based on OE pin.
  - C. All pulses are supplied at pulse repetition rate  $\leq 10$ MHz.
  - D. Inputs are measured separately one transition per measurement.
  - E.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD}$ .

Figure 1. Load Circuit and Voltage Waveforms

## Ordering Information

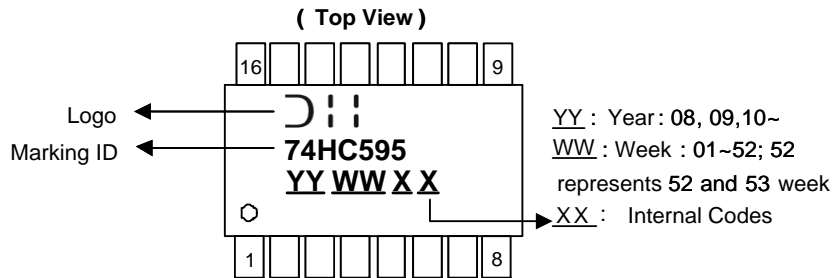


Part Number	Package Code	Packaging	7" Tape and Reel (Note 6)	
			Quantity	Part Number Suffix
74HC595S16-13	S16	SO-16	2500/Tape & Reel	-13
74HC595T16-13	T16	TSSOP-16	2500/Tape & Reel	-13

Note: 6. The taping orientation is located on our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

## Marking Information

(1) SO-16, TSSOP16

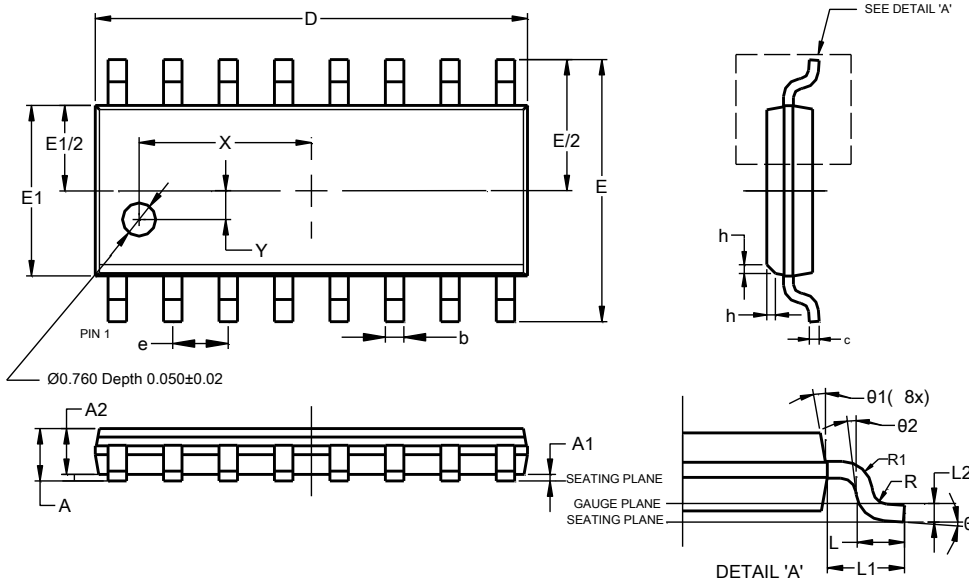


Part Number	Package
74HC595S16	SO-16
74HC595T16	TSSOP-16

# Package Outline Dimensions (All dimensions in mm.)

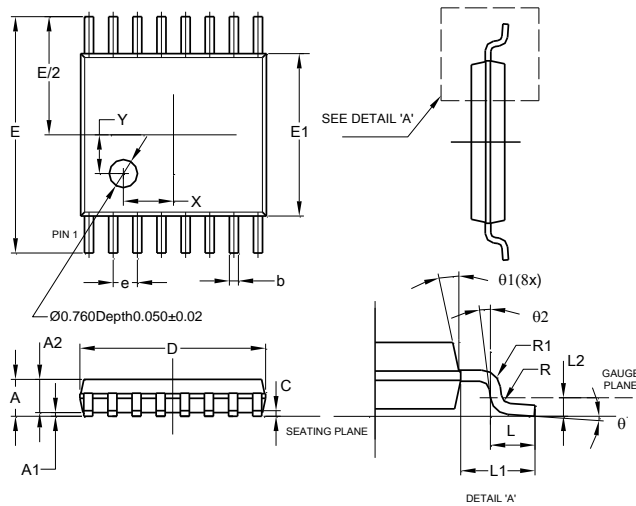
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

## Package Type: SO-16



SO-16			
Dim	Min	Max	Typ
A	--	1.260	--
A1	0.10	0.23	--
A2	1.02	--	--
b	0.31	0.51	--
c	0.10	0.25	--
D	9.80	10.00	--
E	5.90	6.10	--
E1	3.80	4.00	--
e	1.27 BSC		
h	0.15	0.25	0.20
L	0.40	1.27	--
L1	1.04 REF		
L2	0.25 BSC		
R	0.07	--	--
R1	0.07	--	--
X	3.945 REF		
Y	0.661 REF		
θ	0°	8°	--
θ1	5°	15°	--
θ2	0°	--	--
All Dimensions in mm			

## Package Type: TSSOP-16



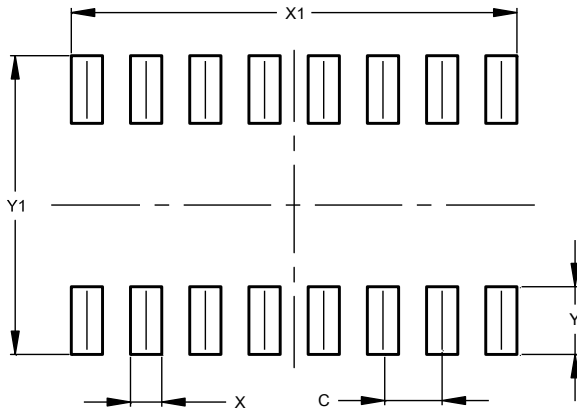
TSSOP-16			
Dim	Min	Max	Typ
A	-	1.08	-
A1	0.05	0.15	-
A2	0.80	0.93	-
b	0.19	0.30	-
c	0.09	0.20	-
D	4.90	5.10	-
E	6.40 BSC		
E1	4.30	4.50	-
e	0.65 BSC		
L	0.45	0.75	-
L1	1.00 REF		
L2	0.25 BSC		
R / R1	0.09	-	-
X	-	-	1.350
Y	-	-	1.050
θ	0°	8°	-
θ1	5°	15°	-
θ2	0°	-	-
All Dimensions in mm			



## Suggested Pad Layout

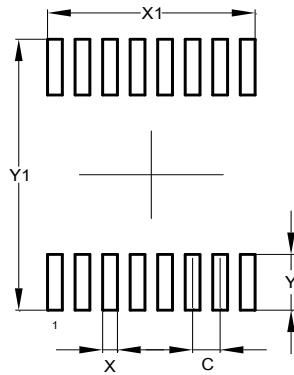
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### Package Type: SO-16



Dimensions	Value (in mm)
C	1.270
X	0.670
X1	9.560
Y	1.450
Y1	6.400

### Package Type: TSSOP-16



Dimensions	Value (in mm)
C	0.650
X	0.350
X1	4.900
Y	1.400
Y1	6.800

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